ELECTRICAL CONTACTS - 2006

Proceedings of

THE FIFTY-SECOND
IEEE HOLM CONFERENCE ON
ELECTRICAL CONTACTS

Sponsored by the
Components, Packaging, and Manufacturing Technology Society
of the Institute of Electrical and Electronics Engineers, Inc.

ELECTRICAL CONTACTS-2006

PROCEEDINGS OF THE 52ND IEEE HOLM CONFERENCE ON ELECTRICAL CONTACTS

PURPOSE

To provide a forum for the presentation and discussion of the latest developments in the field of electric contacts, as well as, the application of recent advances in materials and processes in electrical, electronic and telecommunications equipment.

FOR WHOM

Practicing designers, engineers, physicists, and research scientists-those new to the field and those experienced. The 2006 IEEE Holm Conference will include excellent papers authored by some of the outstanding technical people in this field. The international contributors come from the USA, Austria, Belgium, Canada, China, Finland, France, Germany, Greece, Hong Kong, Italy, Japan, Korea, Netherlands, Norway, Poland, Switzerland, and United Kingdom. These papers will provide the attendees with up-to-date information on a wide range of subjects that makes this conference so attractive to the practicing engineer.

Additionally, the 2006 IEEE Holm Conference will make it possible for any attendee to discuss personally, with any author, either additional details concerning the work presented by the author at the conference or any subject related to the author's field of expertise.

BACKGROUND

The Holm Conference began in 1953 as a forum for the discussion of electrical contact phenomena and related fields. In 1968, the conference was named the Holm Conference in honor of Dr. Ragnar Holm. Dr. Holm, whose contributions to the field of electrical contacts spanned 50 years and forms the foundation of the electrical contacts field, was the inspiration and guide of the Conference from its inception until his death is 1970.

In addition to the Annual Conference, the Conference Organization regularly conducts an intensive one-week course on contacts and participates in the biannual International Conference on Electrical Contacts.

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25 – 27 September 2006
The Delta Centre-Ville Montreal
Montreal, Quebec, Canada H3C 3Z6

The Institute of Electric and Electronics Engineers, Inc.

CPMT

IEEE Catalog Number: 06CH37833
ISBN Casebound: 1-4244-0581-5
Library of Congress: 88-645722

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